

T-P-2 Series – Void Filler (0.50 - 5.00mm Shore 00 45/65)

DATASHEET



T-P-2 Series (0.50 - 5.00mm
Shore 00 45/65)

FEATURES

- Ultra-Soft with High Compressibility
- 1.0 W/mK Thermal Conductivity
- Low Thermal Impedance
- Naturally Tacky

APPLICATIONS

- Electronic Components: IC, CPU, MOS
- LED, Motherboards, Power Supplies, Heat Sinks, LCD-TV, Notebook PC, PC
- Telecom Devices, Wireless Hub, Automotive and Aerospace applications

PROPERTIES	TEST METHOD	UNIT	T-P-2 Series
Material	-	-	Ceramic Powder filled with Silicon Resin
Colour	Visual	-	Light Grey
Thickness (±10%)	ASTM-D374	mm	0.50 – 5.00
Increments of 0.25mm/0.01inch		inch	0.02 – 0.20
Hardness (±10)	ASTM-D2240	Shore 00	45 (≥1.00mm) 65 (<1.00mm)
Thermal Conductivity	ASTM-D5470	W/mK	1.0
Flammability Rating	UL94 IEC 60695-11-10	-	UL94-V0
Dielectric Breakdown Voltage (1mm)	ASTM-D149	kV	≥10
Permittivity (1MHz)	ASTM-D150	-	6.79
Specific Gravity (±0.2)	ASTM-D792	g/cm ³	2.3
Working Temperature	EM344	°C	-40 to 200
Volume Resistance	ASTM-D257	Ohm-cm	10 ¹²
Tensile Strength	ASTM-D412-1998A	MPa	0.45

Note:

1. Customised shapes are available;
2. The above performance data is tested in an environment of 70% humidity, temperature 25°C.
3. This data is intended for reference purposes only. It is recommended that the material is tested to fully evaluate its performance ensuring it is fit for purpose.

Ventec International Group

United Kingdom
Unit 1 Trojan Business Centre,
Tachbrook Park Estate
Leamington Spa, CV34 6RH
Tel: +44 1926-889822

Germany
Morschheimerstrasse 15
67292 Kirchheimbolanden
Tel: +49 6352-753260

Published:
16/07/2019

emithermal@ventec-europe.com
www.ventecamines.com